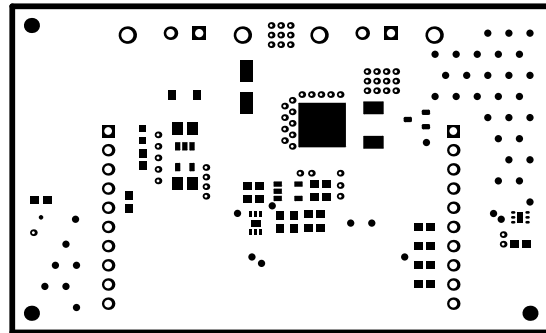
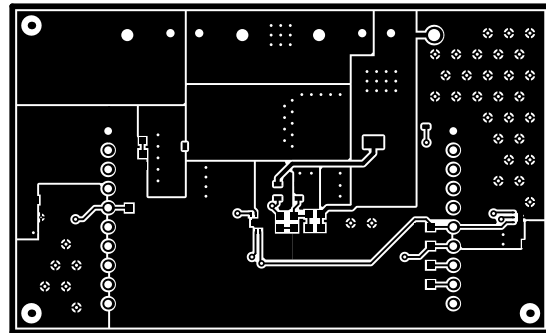


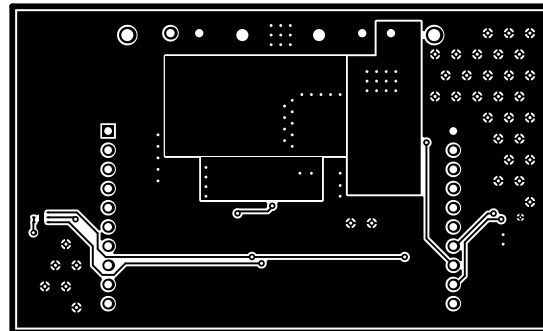
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01539		
PLOT NAME = Top Overlay	GENERATED : 4/26/2018 4:16:09 PM	TEXAS INSTRUMENTS	



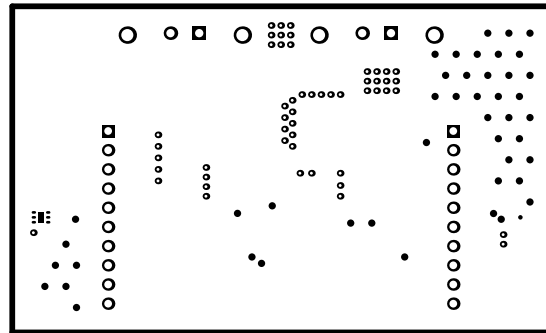
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01539		
PLOT NAME = Top Solder Mask	GENERATED : 4/26/2018 4:16:10 PM	TEXAS INSTRUMENTS	



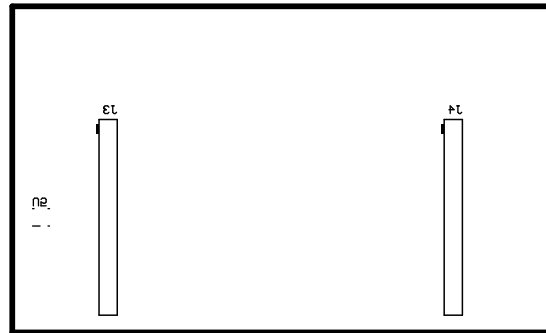
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01539		
PLOT NAME = Top Layer	GENERATED : 4/26/2018 4:16:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01539		
PLOT NAME = Bottom Layer	GENERATED : 4/26/2018 4:16:13 PM	TEXAS INSTRUMENTS	

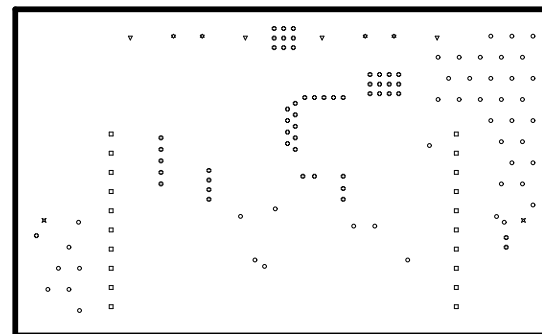


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01539		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/26/2018 4:16:14 PM	TEXAS INSTRUMENTS	

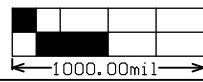


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01539		
PLOT NAME = Bottom Overlay	GENERATED : 4/26/2018 4:16:15 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	2	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	52	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
○	45	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
□	20	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	127 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01539		
PLOT NAME = Drill Drawing	GENERATED : 4/26/2018 4:16:16 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01539	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01539		
PLOT NAME = Board Dimensions	GENERATED : 4/26/2018 4:16:18 PM	TEXAS INSTRUMENTS	

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